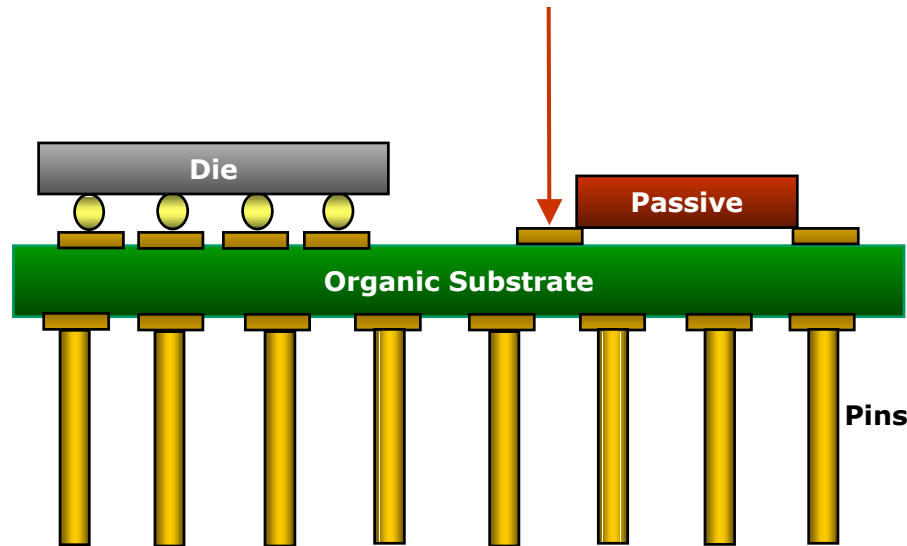


CPU Changes for RoHS Compliance (OPGA only)



Solder for Attachment of Passives

- Converting to lead-free solder
- Only change required to make CPU RoHS Compliant
- Capacitors are already lead free



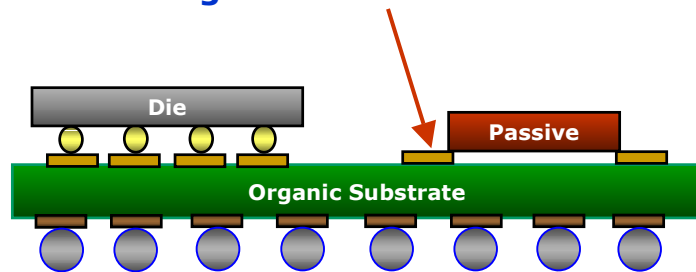
Flip Chip OPGA (lid may be present)

Note: Changes will not affect the fit, electrical datasheet, functionality/performance specifications, and quality or reliability.

8000 Series Chipsets Changes for RoHS Compliance



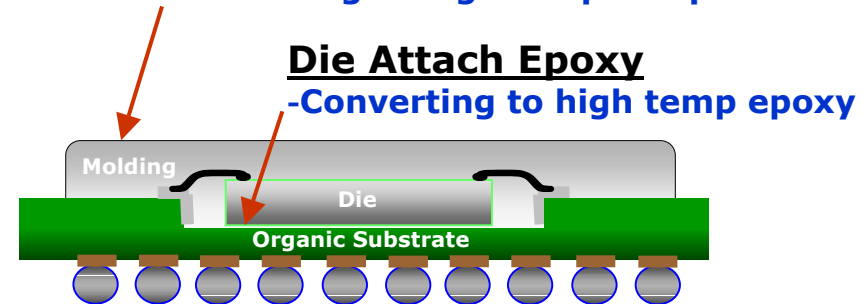
Solder for Attachment of Passives -Converting to Pb-free solder



Solderballs for BGA -Converting to Pb-free solder

Flip Chip BGA (lid not shown)
(AMD-8131, AMD-8132, AMD-8151)

Molding Compound -Converting to high temp compound



Solderballs for BGA -Converting to Pb-free solder

Wire bond BGA
(AMD-8111)

Note: Changes will not affect the fit, electrical datasheet, functionality/performance specifications, and quality or reliability.